

**Amendments to the Specification:**

Please replace the paragraph beginning on page 13, line 4 with the following rewritten paragraph:

[0041] The preferred type of the conductive composition of the present invention is a conductive paste. The conductive paste can be suitably realized by further compounding a binder resin and a solvent dissolving the binder resin in addition to the aforementioned metal particle and the metal oxide particle. The examples of the binder resin are cellulose resin such as ethyl cellulose, rosin group resin, ~~polyvinyl~~ polyvinyl group resin, butyral group resin, polyester group resin, acryl group resin, epoxy group resin, polyamide group resin, polyurethane group resin, alkyd group resin, maleic acid group resin, petroleum group resin, and the like. Among these, the preferable ones are acryl group resin and cellulose group resin such as ethyl cellulose. Additionally, the solvent is not particularly limited as long as it can dissolve the above-mentioned binder resin, however, the examples are alcohols such as ethanol, aromatic hydrocarbons such as toluene and xylene, ethers, ketones, chlorohydrocarbons, and the like. The binder resin and the solvent may be each used alone or used as a mixture of two or more kinds thereof.

Please replace the paragraph beginning on page 13, line 24 with the following rewritten paragraph:

[0042] Moreover, when the conductive composition of the present invention is used as the conductive paste, it may further comprise a surfactant, a plasticizer, an ~~antistatic~~ antistatic agent, an antifoaming agent, an antioxidant, a slip additive, a curing agent, and the like as additives if required.